

# **Product Change Notification - LIAL-17HGTR431**

Date:

14 Dec 2018

**Product Category:** 

Others; 8-bit Microcontrollers

**Affected CPNs:** 



# **Notification subject:**

CCB 3385 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 28L SOIC package.

**Notification text:** 

**PCN Status:** 

Final notification.

# **PCN Type:**

Manufacturing Change

# **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

**NOTE:** For your convenience Microchip includes identical files in two formats (.pdf and .xls)

#### **Description of Change:**

Qualification of MTAI as a new assembly site for selected Atmel products available in 28L SOIC package.

### **Pre Change:**

Assembled at ANAP using palladium gold wire (AuPd) material and 8290 die attach material.

#### **Post Change:**

Assembled at MTAI using gold (Au) bond wire material and 3280 die attach material.

**Pre and Post Change Summary:** 

	Pre Change	Post Change			
Assembly Site	Amkor Technology	Microchip Technology			
	Philippine (P1/P2), INC.	Thailand (HQ)			
	(ANAP)	(MTAI)			
Wire material	AuPd	Au			
Die attach material	8290	3280			
Molding compound	G600	G600			
material	G000	G000			
Lead frame material	C194	C194			

### **Impacts to Data Sheet:**

None

### **Change Impact:**

None



## **Reason for Change:**

To improve on time delivery performance by qualifying MTAI as a new assembly site.

# **Change Implementation Status:**

In Progress

### **Estimated First Ship Date:**

December 28, 2018 (date code: 1852)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

### **Time Table Summary:**

	May 2018					December 2018				
Workweek	18	19	20	21	22	->	49	50	51	52
Initial PCN Issue Date					X					
Qual Report Availability								X		
Final PCN Issue Date								X		
Estimated Implementation										
Date										^

# Method to Identify Change:

Traceability code

### **Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

## **Revision History:**

May 30, 2018: Issued initial notification.

**December 14, 2018:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on December 28, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

# Attachment(s):

PCN\_LIAL-17HGTR431\_QUAL REPORT.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and



make the applicable selections.

LIAL-17HGTR431 - CCB 3385 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 28L SOIC package.

Affected Catalog Part Numbers (CPN)

AT83C5136DXN-TIRUL AT89C5115-TISUM AT89C5131A-TIRUL AT89C5131A-TISUL AT89C51CC02CA-TISUM AT89C51CC02UA-TISUM

Date: Thursday, December 13, 2018